

2:1 Mux/DeMux High Bandwidth HDMI™ 2.1 Compliant Signal Switch

Descriptions

The RLCS422 is an 8-to-4-channel Mux/DeMux switch designed for DVI/HDMI™ standards and TMDS signal processing. It multiplexes differential signals bidirectionally with minimal signal attenuation, ensuring low skew and high noise isolation. Its high bandwidth supports next-gen HDTV and PC graphics. Three channels handle data (DVI video or HDMI audio/video), while one manages clock signals for TMDS decoding. The switch works passively at both driver (e.g., LCD, projector, TV) and receiver (e.g., DVD, STB) ends. Its wide voltage range enables DC-coupled multi-standard operation, saving space by eliminating AC capacitors. It also supports 0V-3.3V CMOS signals up to 1MHz and switches DDC/HPD signals.

Features

- 4-Differential Channel 2:1 Mux/DeMux
- HDMI 2.1 compatible
- High Bandwidth: 5.7GHz @ -3dB BW
- Supports both AC coupled and DC coupled signals
- Isolation: -40dB @ 2.0 Gbps
- Crosstalk: -31dB @ 2.0 Gbps
- ESD Tolerance: 2kV HBM
- Low bit-to-bit skew, Bidirectional
- Supports DDC with HPD channel mux/demux @ HDMI
- Supports 720 Mbps high-speed DP AUX @ DP

Applications

- Routing of HDMI 2.1 video signals with low signal attenuation between source and sink for 4K2K ultra high definition video display and broadcast video equipment.
- Routing of DisplayPort video signals with low signal attenuation between source and sink for PC and monitor.

Order information

Package		Part Number	Top-Side Marking
QFN 5×5-40L	Tape and Reel	RLCS422QN40/R6	RLCS422

Block Diagram and Pin Configuration

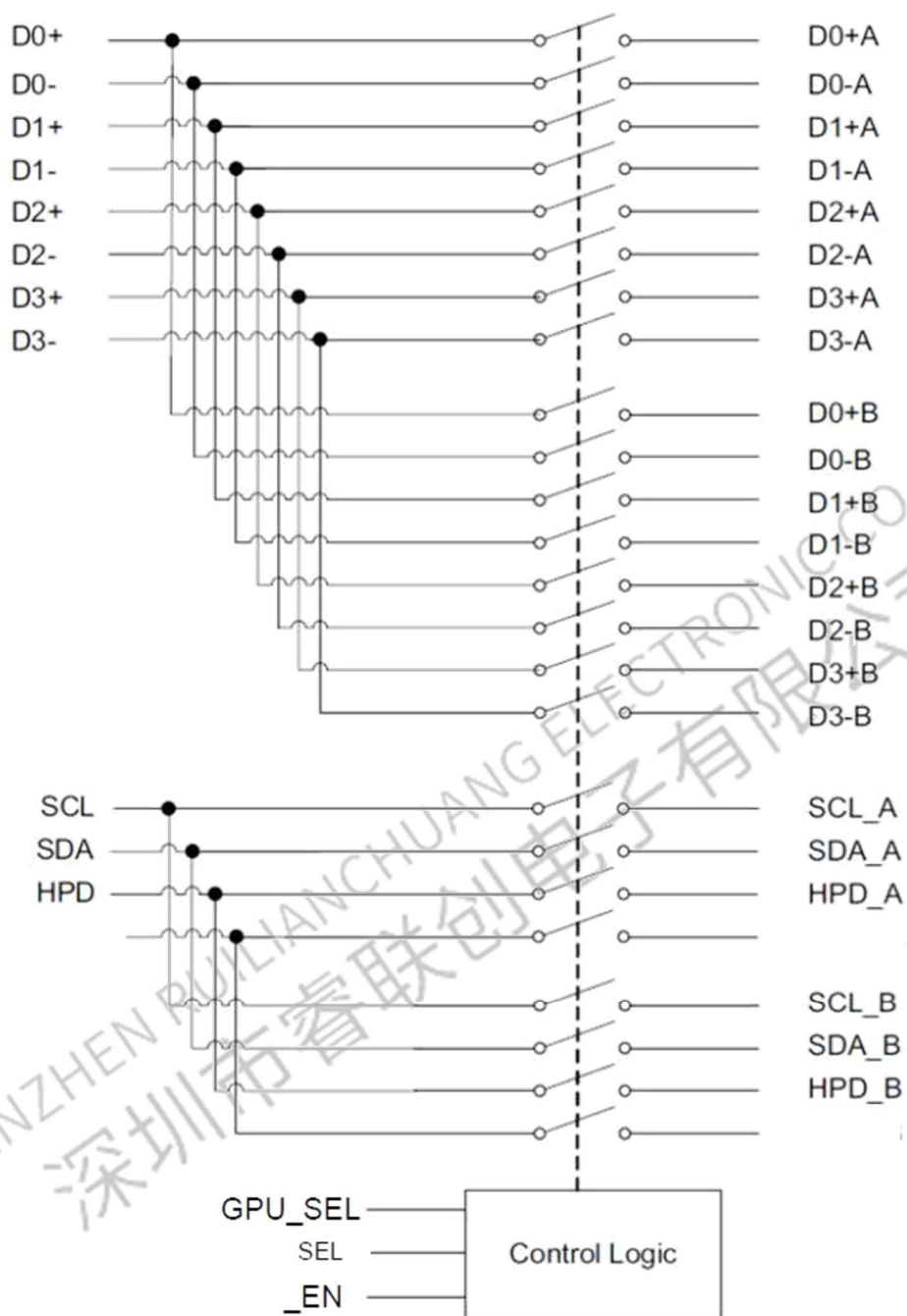


Fig.1 Block Diagram

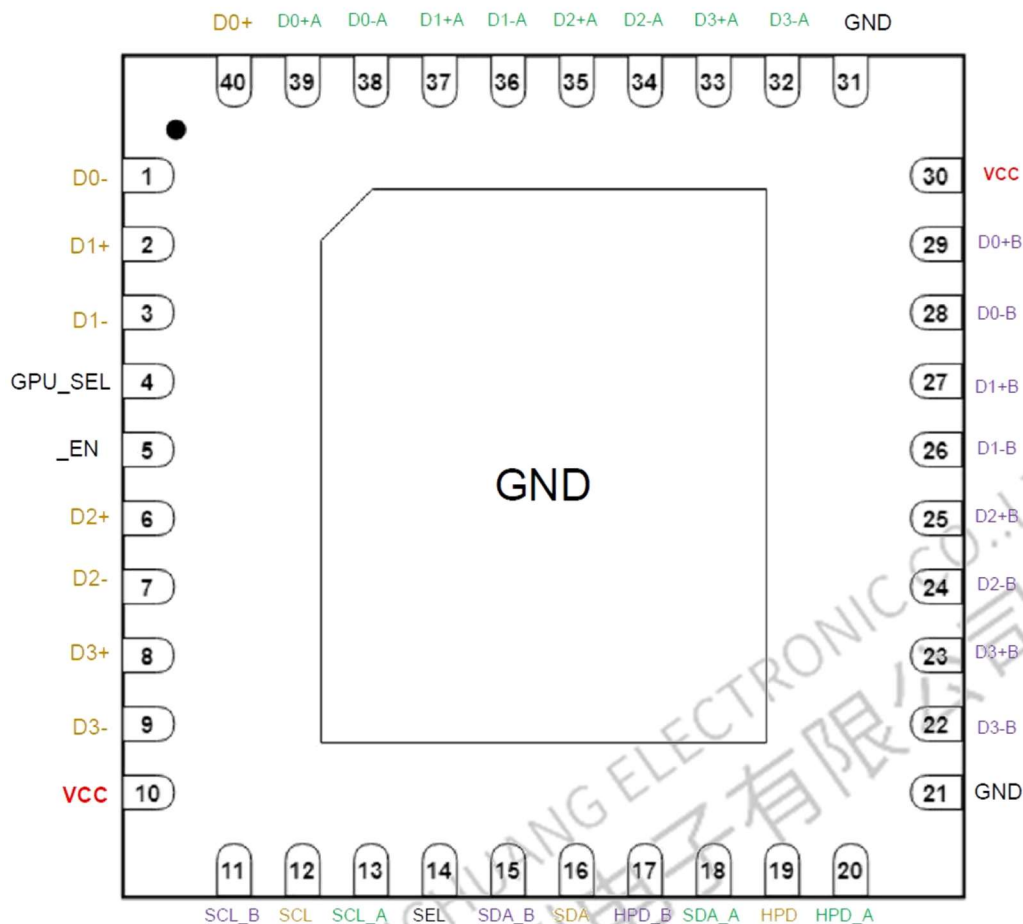


Fig.2 Top-Through View

Truth Table

_EN	GPU_SEL	D0-D3
High	X	Hi-Z
Low	Low	A
Low	High	B

SEL	SCL	SDA	HPD
X	Hi-Z	Hi-Z	Hi-Z
Low	A	A	A
High	B	B	B

Pin Description

Pin#	Pin Name	Signal Type	Description
40	D0+	I/O	Positive differential signal 0 for COM port
1	D0-	I/O	Negative differential signal 0 for COM port
2	D1+	I/O	Positive differential signal 1 for COM port
3	D1-	I/O	Negative differential signal 1 for COM port
4	GPU_SEL	I	GPU Switch logic control
5	_EN	I	Chip Enable, Active low
6	D2+	I/O	Positive differential signal 2 for COM port
7	D2-	I/O	Negative differential signal 2 for COM port
8	D3+	I/O	Positive differential signal 3 for COM port
9	D3-	I/O	Negative differential signal 3 for COM port
10,30	VCC	Power	Supply Voltage
11	SCL_B	I/O	DDC clock for port B
12	SCL	I/O	DDC clock for COM port
13	SCL_A	I/O	DDC clock for port A
14	SEL	I	Switch logic control for DDC/AUX and HPD
15	SDA_B	I/O	DDC data for port B
16	SDA	I/O	DDC data for COM port
17	HPD_B	I/O	Hot plug detect for B port
18	SDA_A	I/O	DDC data for port A
19	HPD	I/O	Hot plug detect for COM port
20	HPD_A	I/O	Hot plug detect for port A
21,31	GND	Ground	Ground
22	D3-B	I/O	Negative differential signal 3 for port B
23	D3+B	I/O	Positive differential signal 3 for port B
24	D2-B	I/O	Negative differential signal 2 for port B
25	D2+B	I/O	Positive differential signal 2 for port B
26	D1-B	I/O	Negative differential signal 1 for port B
27	D1+B	I/O	Positive differential signal 1 for port B
28	D0-B	I/O	Negative differential signal 0 for port B
29	D0+B	I/O	Positive differential signal 0 for port B
32	D3-A	I/O	Negative differential signal 3 for port A
33	D3+A	I/O	Positive differential signal 3 for port A
34	D2-A	I/O	Negative differential signal 2 for port A
35	D2+A	I/O	Positive differential signal 2 for port A
36	D1-A	I/O	Negative differential signal 1 for port A
37	D1+A	I/O	Positive differential signal 1 for port A
38	D0-A	I/O	Negative differential signal 0 for port A
39	D0+A	I/O	Positive differential signal 0 for port A

Maximum Ratings

(Above which useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	-65°C to +150°C
Junction Temperature	125°C
Supply Voltage to Ground Potential	-0.5V to +5.5V
High Speed Data Channel D0~D3	-0.5V to 3.8V
CEC, SCL, SDA, HPD	-0.5V to 5.5V
DC Input Voltage	-0.5V to VCC
DC Output Current	120mA
Power Dissipation	0.5W

Notes:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Electrical Characteristics

Parameter			Test conditions ⁽¹⁾	Min	Typ. ⁽²⁾	Max	Unit
PORT A							
R _{ON}	ON-state resistance	D0 to D3	V _{CC} =3V, 1.5V≤V _{I/O} ≤V _{CC} , I _{I/O} =-40mA		6.5	9.5	Ω
		SCL,SDA,HPD,CEC			6	9.5	Ω
R _{ON(flat)}	ON-state resistance flatness	All I/O	V _{CC} =3V, V _{I/O} =1.5V and V _{CC} ,I _{I/O} =-40mA		1.5		Ω
ΔR _{ON}	On-state resistance match between high-speed channels	D0 to D3	V _{CC} =3V,1.5V≤V _{I/O} ≤V _{CC} ,I _{I/O} =-40mA		0.4	1	Ω
I _{OFF}	Leakage under power off	All outputs	V _{CC} =0V, V _{I/O} =0V to 3.6V , V _{IN} =V to 5.5V	±10			uA
PORT B							
R _{ON}	ON-state resistance	D0 to D3	V _{CC} =3V, 1.5V≤V _{I/O} ≤V _{CC} , I _{I/O} =-40mA		8.2	10.5	Ω
		SCL,SDA,HPD,CEC			6	9.5	Ω
R _{ON(flat)}	ON-state resistance flatness	All I/O	V _{CC} =3V, V _{I/O} =1.5V and V _{CC} ,I _{I/O} =-40mA		1.5		Ω
ΔR _{ON}	On-state resistance match between high-speed channels	D0 to D3	V _{CC} =3V,1.5V≤V _{I/O} ≤V _{CC} ,I _{I/O} =-40mA		0.4	1	Ω
I _{OFF}	Leakage under power off	All outputs	V _{CC} =0V, V _{I/O} =0V to 3.6V , V _{IN} =V to 5.5V			±10	uA
DIGITAL INPUTS(SEL1,SEL2,EN1,EN2)							
V _{IH}	High-level control input voltage	SEL1, SEL2, EN1, EN2		1.4			V
V _{IL}	LOW-level control input voltage					0.5	V
V _{IH}	Digital input high leakage current		V _{CC} =3.6V, V _{IN} =V _{CC}			±10	uA
V _{IL}	Digital input low leakage current		V _{CC} =3.6V, V _{IN} =GND			±10	uA
SUPPLY							
I _{CC}	VCC supply current	V _{CC} =3.6V, I _{I/O} =0,Normal operation mode, _ENx=L			100		uA
I _{CC, PD}	VCC supply current in power-down mode	V _{CC} =3.6V, I _{I/O} =0, _ENx=H			2		uA

Notes:

1. V_I, V_O, I_I, and I_O refer to I/O pins, V_{IN} refers to the control inputs.
2. All typical values are at V_{CC} = 3.3 V (unless otherwise noted), T_A = 25°C.
3. R_{ON(FLAT)} is the difference of R_{ON} in a given channel at specified voltages.
4. ΔR_{ON} is the difference of R_{ON} from center port to any other ports.

Switching Characteristics (TA= -40°C to +105°C, VCC=3.3V±10%)

Parameter	Description	Min.	Typ.	Max	Unit
T _{pd}	Propagation delay (input pin to output pin) on all channels		80		ps
t _{b-b}	Bit-to-bit skew within the same differential pair of Dx± channels		5	7	ps
t _{ch-ch}	Channel-to-channel skew of Dx+ channels			35	ps
Tsw a-b	Time it takes to switch from port A to port B			0.1	us
Tsw b-a	Time it takes to switch from port B to port A			0.1	us
Tstart up	VCC valid to channel enable			10	us
Twake up	Enabling output by changing OE from low to High			10	us

Dynamic Electrical Characteristics Over Operating Range (TA= -40° to +105°C,
VCC=3.3V±10%)

Parameter	Description	Test conditions	Min.	Typ.	Max	Unit
X _{TALK}	Crosstalk on High Speed Channels	See Fig.3 for Measurement setup	f = 3.0GHz	-25	-22	dB
			f = 2.7GHz	-28	-25	
			f = 1.7GHz	-31	-28	
			f = 1.35GHz	-32	-28	
O _{IRR}	OFF Isolation on High Speed Channels	See Fig.4 for Measurement setup	f = 3.0GHz	-22	-20	dB
			f = 2.7GHz	-22	-20	
			f = 1.7GHz	-29	-26	
			f = 1.35GHz	-30	-27	
I _{LOSS}	Different Insertion Loss on High Speed Channels	@3.0GHz(see Fig.5)	-2.0	-1.7		dB
		@5.4GHz(see Fig.5)	-2.0	-1.7		
R _{LOSS}	Different Return Loss on High Speed Channels	@3.0GHz(6.0Gbps)		-16.0	-14	dB
		@2.7GHz(5.4Gbps)		-14.0	-12.5	
BW	Bandwidth -3dB	see Fig.5		5.7		GHz

Note:

- For Max. or Min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device type.
- Typical values are at VCC=3.3V,TA=25°C ambient and maximum loading.

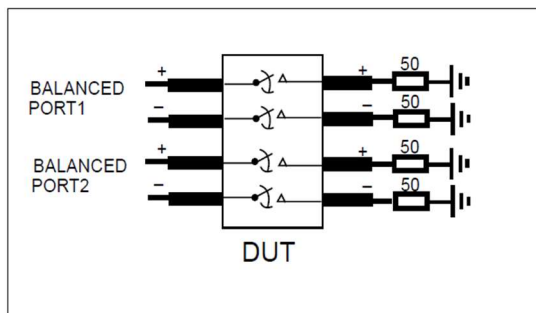


Fig.3 Crosstalk Setup

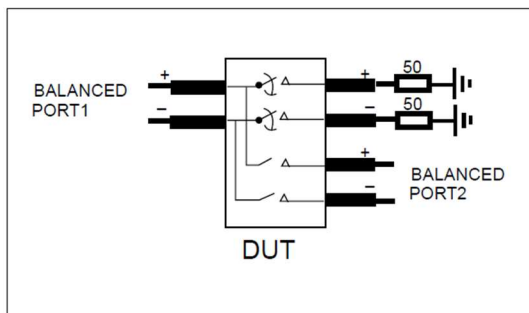


Fig.4 OFF-isolation

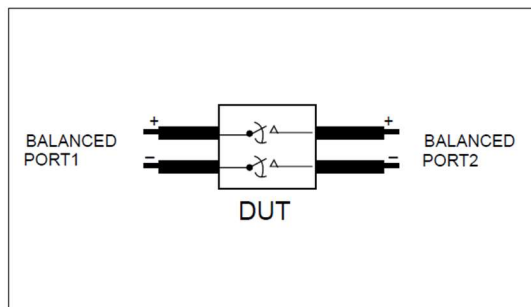
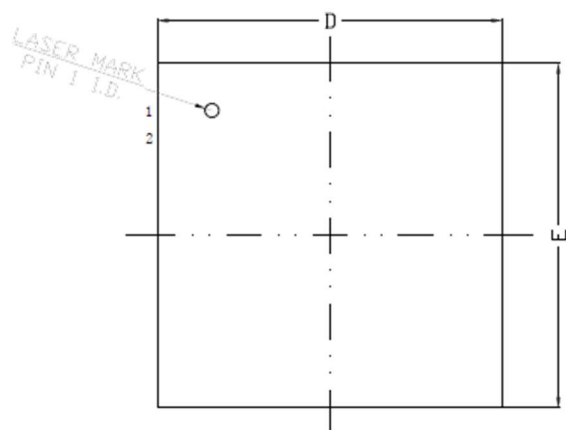


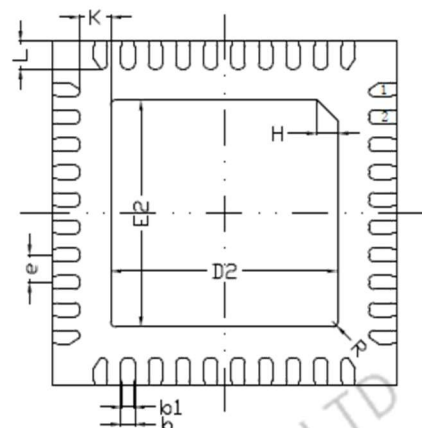
Fig.5 Different Insertion Loss

SHENZHEN RUILIANCHUANG ELECTRONIC CO.,LTD
深圳市睿联创电子有限公司

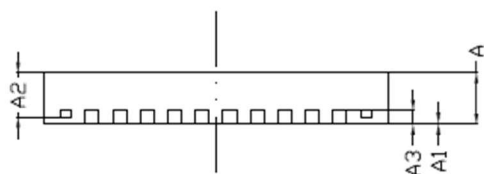
Package Outline Dimensions



TOP VIEW



BOTTOM VIEW



SIDE

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	—	0.02	0.05
A2	0.60	0.65	0.70
A3	0.20REF		
b	0.15	0.20	0.25
b1	0.18REF		
D	4.90	5.00	5.10
E	4.90	5.00	5.10
D2	3.20	3.30	3.40
E2	3.20	3.30	3.40
e	0.40BSC		
H	0.25	0.30	0.35
K	0.45REF		
L	0.35	0.40	0.45
R	0.075REF		

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